

N-Channel Enhancement Mode MOSFET

1. Product Information

Features

- Fast Switching Capability
- Excellent R_{DSON}
- Low Gate Charge

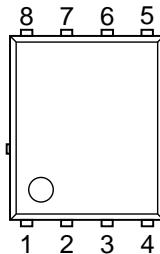
Pin Description

Pin	Description
1,2,3	Gate(G)
4	Drain(D)
5,6,7,8	Source(S)

Applications

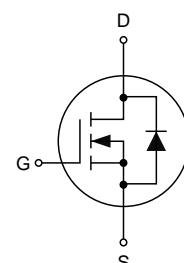
- Uninterruptible Power Supply
- Load Switch
- Automotive Lighting

Simplified Outline



Top View
PDFN5x6-8L

Symbol



Quick reference

- V_{DS} = 200 V
- I_D = 50 A
- R_{DSON} ≤ 52 mΩ @ V_{GS} = 10 V (Type: 43 mΩ)

Package Marking and Ordering Information

Product Name	Package	Marking	Reel size	Tape width	Quantity (pcs)
KJ50N20G	PDFN 5x6-8L	KJ50N20 XXXXXX	13"	12 mm	5000

2. Absolute Maximum Ratings (T_C=25°C unless otherwise noted)

Symbol	Parameter	Values	Unit
V _{DS}	Drain-Source Voltage	200	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current Continuous, T _C =25°C, V _{GS} =10 V	50	A
	Drain Current Continuous, T _C =100°C, V _{GS} =10 V	35	A
I _{DM}	Pulsed Drain Current	200	A
E _{AS}	Single Pulse Avalanche Energy	279	mJ
P _D	Power Dissipation	52.5	W
T _J , T _{STG}	Operating Junction and Storage Temperature Range	-55 to 150	°C
R _{thJA}	Thermal Resistance, Junction-to-Ambient	28	°C/W
R _{thJC}	Thermal Resistance, Junction-to-Case	2.0	°C/W

3. Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=250 \mu\text{A}$	200	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=200 \text{ V}, V_{\text{GS}}=0 \text{ V}$	-	-	1	μA
		$V_{\text{DS}}=200 \text{ V}, T_J=75^\circ\text{C}$	-	-	10	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{DS}}=0 \text{ V}, V_{\text{GS}}=\pm 20 \text{ V}$	-	-	± 100	nA
$V_{\text{GS(th)}}$	Gate-Source Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250 \mu\text{A}$	2.5	3.5	4.5	V
$R_{\text{DS(ON)}}$	Drain-Source On-Resistance	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=10 \text{ A}$	-	43	52	$\text{m}\Omega$
R_g	Gate Resistance	$f=1.0 \text{ MHz}$	-	1.0	-	Ω
C_{iss}	Input Capacitance	$V_{\text{DS}}=100 \text{ V}, V_{\text{GS}}=0 \text{ V}, f=1.0 \text{ MHz}$	-	1455	-	pF
C_{oss}	Output Capacitance		-	114	-	
C_{rss}	Reverse Transfer Capacitance		-	9.2	-	
Q_g	Total Gate Charge	$V_{\text{DS}}=100 \text{ V}, V_{\text{GS}}=7.5 \text{ V}, I_{\text{D}}=10 \text{ A}$	-	18.5	-	nC
Q_{gs}	Gate-Source Charge		-	6.5	-	
Q_{gd}	Gate-Drain Charge		-	6	-	
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=100 \text{ V}, V_{\text{GEN}}=10 \text{ V}, I_{\text{D}}=10 \text{ A}, R_{\text{G}}=1 \Omega, R_{\text{L}}=10 \Omega,$	-	11	-	ns
t_r	Turn-on Rise Time		-	19	-	
$t_{\text{d(off)}}$	Turn-off Delay Time		-	16	-	
t_f	Turn-off Fall Time		-	9	-	
I_s	Maximum Continuous Drain-Source Diode Forward Current	-	-	50	A	
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	-	-	150	A	
V_{SD}	Diode Forward Voltage	$I_{\text{S}}=5 \text{ A}$	-	-	1.1	V
t_{rr}	Reverse Recovery Time	$I_{\text{S}}=10 \text{ A}, V_{\text{GS}}=0 \text{ V}, dI/dt=100 \text{ A}/\mu\text{s}$	-	167	-	ns
Q_{rr}	Reverse Recovery Charge		-	574	-	

Note:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2 OZ copper.
2. The E_{AS} data shows Max. rating. The test condition is $V_{\text{DD}}=72 \text{ V}, V_{\text{GS}}=10 \text{ V}, I_{\text{AS}}=40 \text{ A}, R_{\text{G}}=25 \Omega, L=0.1 \text{ mH}$.
3. Pulse Test: Pulse width $\leq 300 \mu\text{s}$, Duty cycle $\leq 2\%$.
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

4. Typical Characteristics

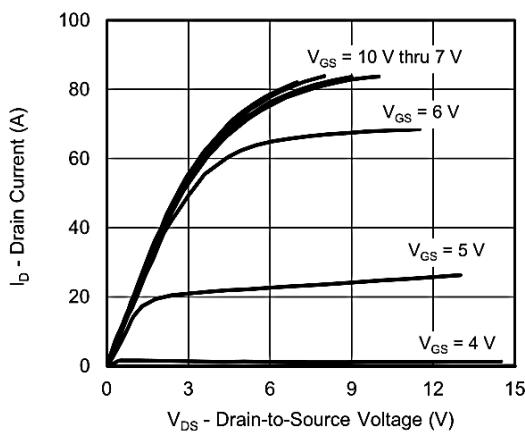


Figure 1. Output Characteristics

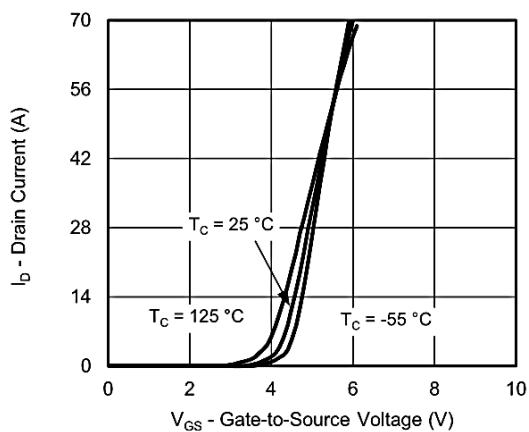


Figure 2. Transfer Characteristics

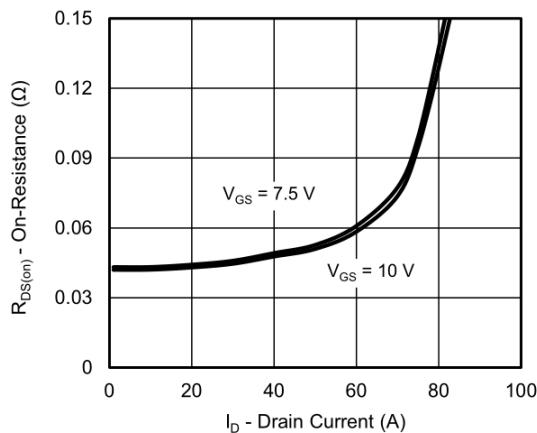


Figure 3. On-Resistance vs. Drain Current

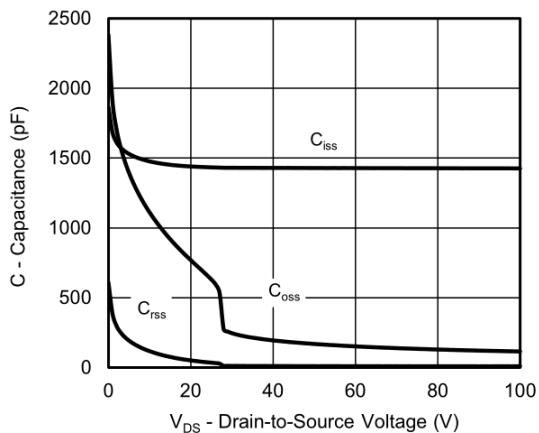


Figure 4. Capacitance

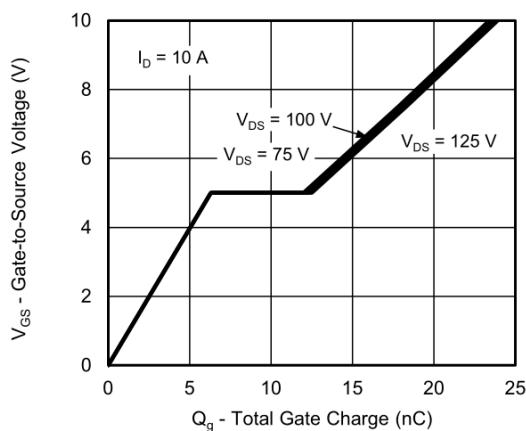


Figure 5. Gate Charge

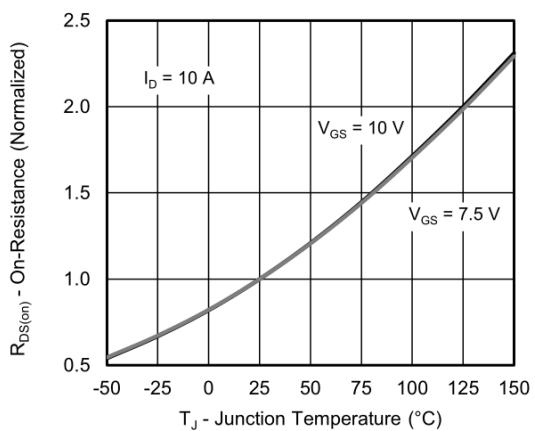


Figure 6. On-Resistance vs. Junction Temperature

4. Typical Characteristics (cont.)

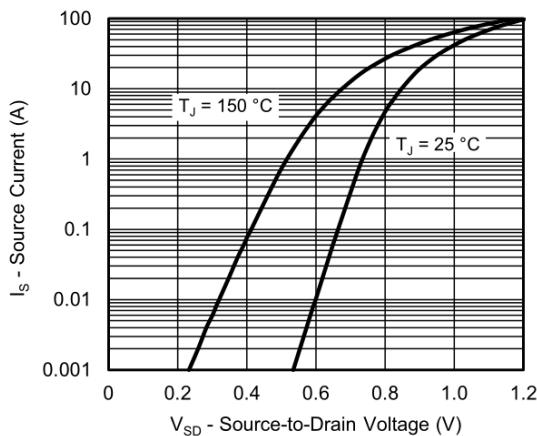


Figure 7. Source-Drain Diode Forward Voltage

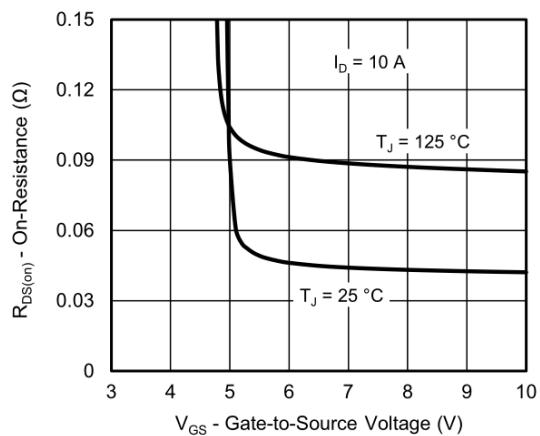


Figure 8. On-Resistance vs. Gate-to-Source Voltage

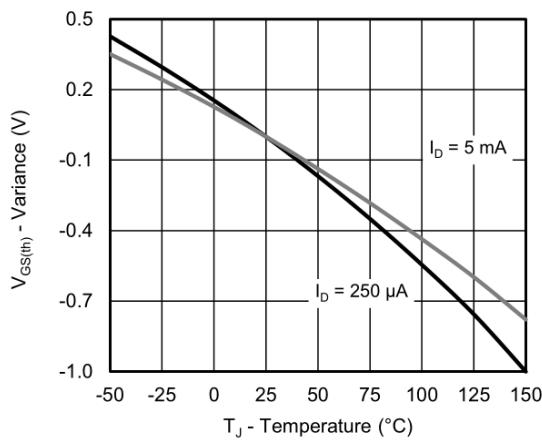


Figure 9. Threshold Voltage

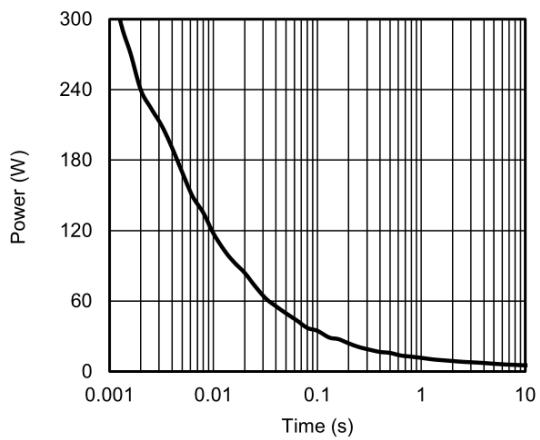


Figure 10. Single Pulse Power, Junction-to-Ambient

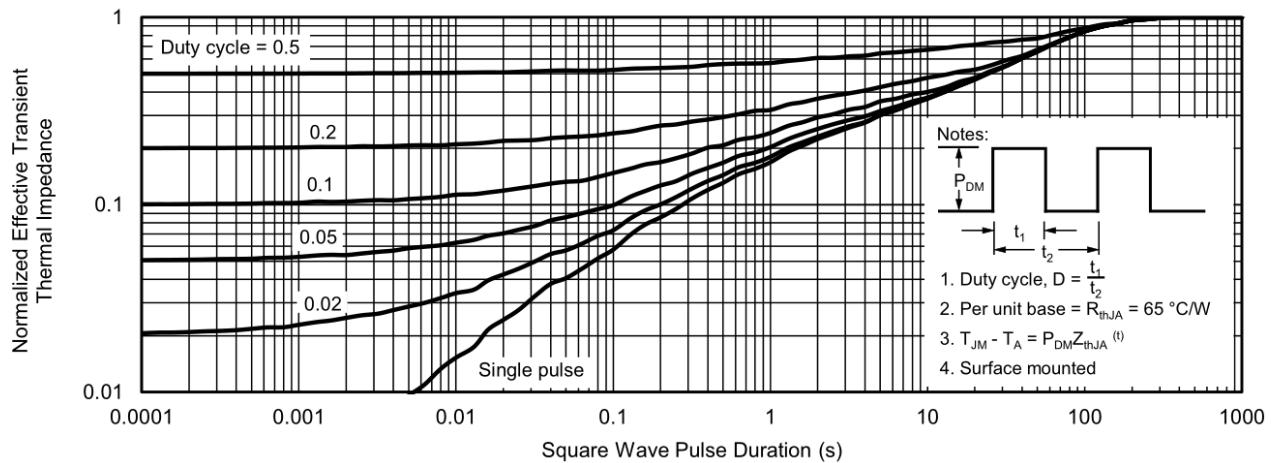
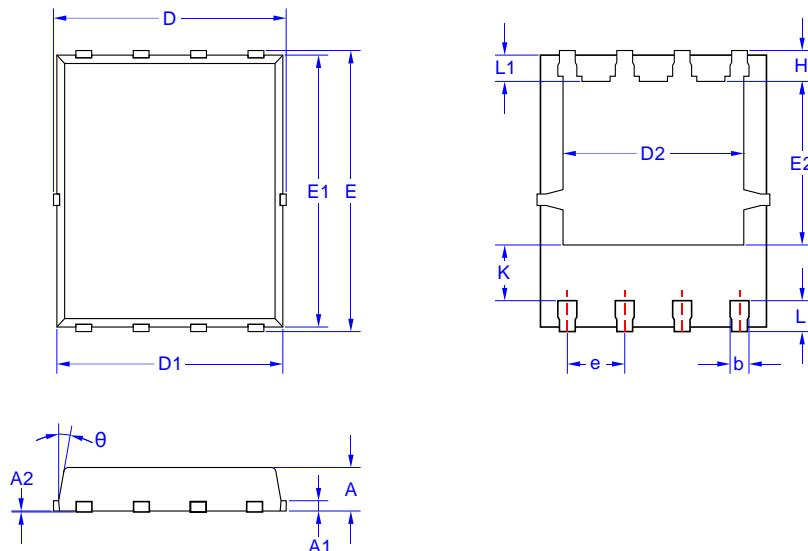


Figure 11. Normalized Thermal Transient Impedance, Junction-to-Ambient

5. Package Mechanical Data

PDFN 5x6-8L Package



Symbol	Dimensions in Millimeters		
	MIN	NOM	MAX
A	0.900	-	1.100
A1			0.254 REF
A2	0	-	0.050
b	0.350	-	0.450
D	4.944	-	5.096
D1	4.824	-	4.976
D2	3.910	-	4.110
E	5.974	-	6.126
E1	5.674	-	5.826
E2	3.375	-	3.575
e	1.270 TYP		
H	0.549	-	0.726
K	1.190	-	1.390
L	0.534	-	0.711
L1	0.424	-	0.576
θ	8°	-	12°